

Combine Type Connector (for Memory Stick Duo™, miniSD™ Card)

SCJD Series



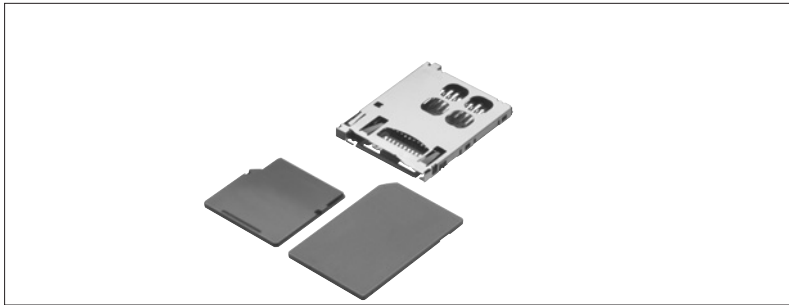
Push-in push-out eject mechanism applicable to two types of media.

For SD Memory Card

For miniSD™ Card

For microSD™ Card

For W-SIM



For Memory Stick Micro™

For Memory Stick™

Combine Type

For Compact Flash™

For PC cards supporting CardBus

For Express Card™

For CMOS Camera Module

Features

- Applicable to two memory card standards - Memory Stick Duo™ and miniSD™ Card.
- Push-push ejection mechanism applied in both card types.
- Same insertion and ejection position applied for both cards.

Applications

- For mobile phones, various personal digital assistants, desktop PCs, notebook PCs, digital still cameras, digital camcorders, and printers.
- For home audio equipment (TVs and set top boxes)
- For audio systems
- For portable memory players

Typical Specifications

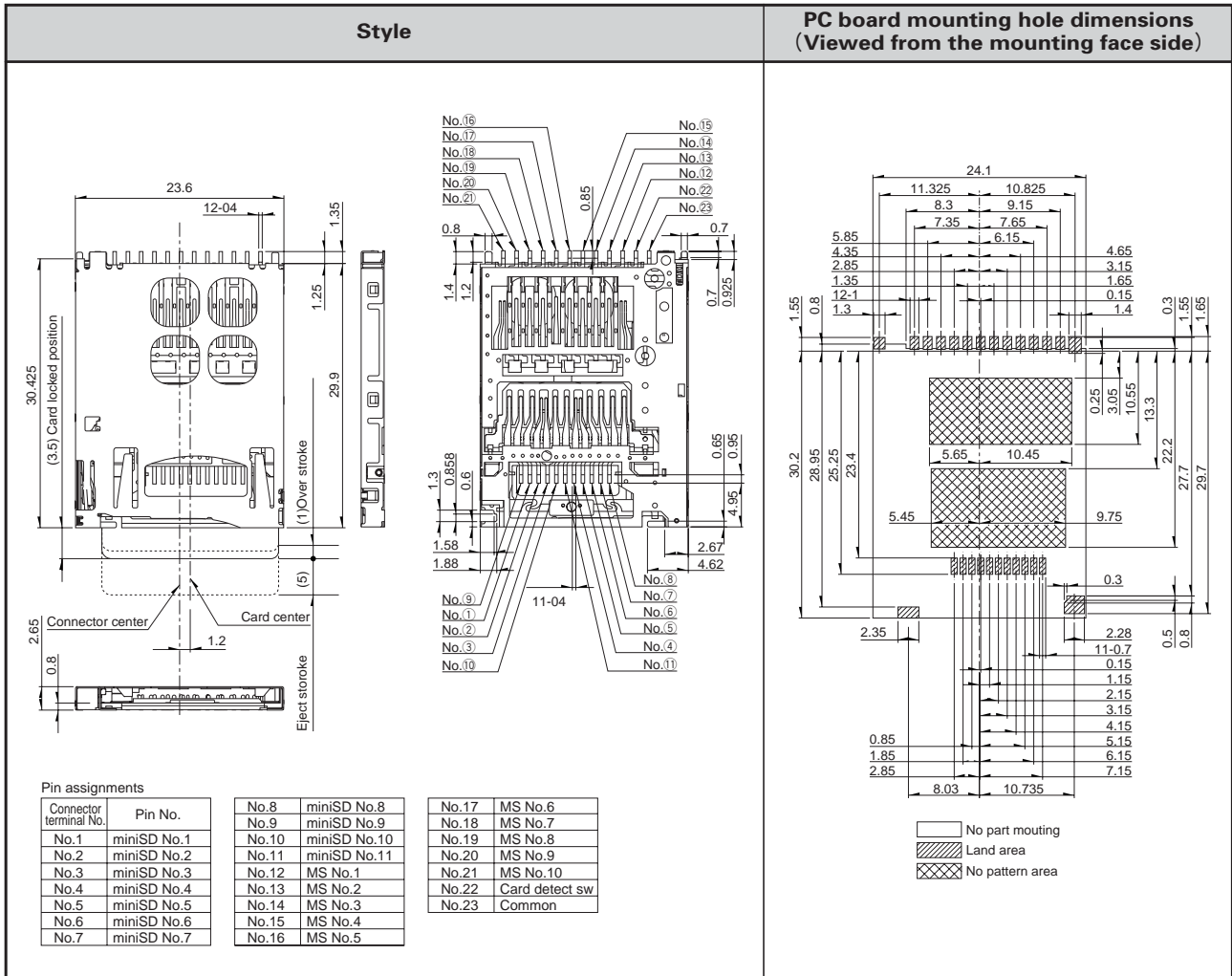
Items		Specifications	
Structure	Applicable media	Memory Stick Duo™	
		miniSD™ Card	
	Mounting type	Surface mounting type	
	Mounting style	Standard mount	
	Media ejection structure	Push-push type	
Performance	Operating temperature range	-10°C to +60°C	
	Voltage proof	250V AC 1minute	
	Insulation resistance (Initial)	1,000MΩ min.	
	Contact resistance (Initial)	Connector contacts	100mΩ max.
		Detection switch	500mΩ max.
Insertion and removal cycle	10,000cycles (mini SD™ Card) 12,000cycles (Memory Stick Duo™)		

Product Line

Media ejection structure	Mounting system	Stand-off (mm)	Packing system	Product No.
Push-push type	Standard mount	0	Taping	SCJD1A0101

Dimensions

Unit:mm

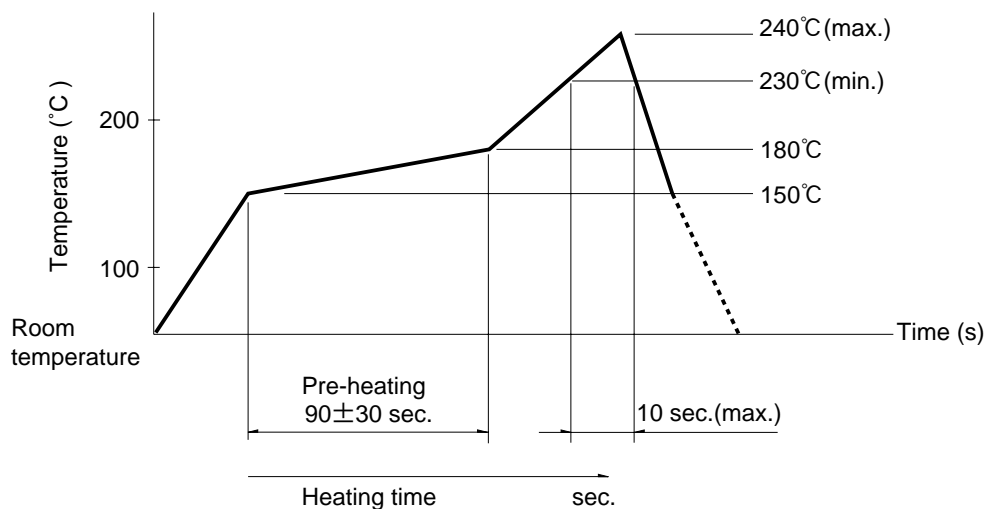


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Soldering Conditions

Example of Reflow Soldering Condition (Reference)

1. Heating method: Double heating method with infrared heater.
2. Temperature measurement: Thermocouple 0.1 to 0.2 ϕ CA (K) or CC (T).
3. Temperature profile (Surface of products).



Cautions

1. When soldering terminals, there is a danger that load placed on the terminals may cause rattle, deformation or electrical degradation to occur depending on the conditions. Caution is therefore required.
2. Avoid use of water-soluble soldering flux, since it may corrode the product.
3. Check and conform to reflow soldering requirements under actual mass production conditions.
4. PC board warping may alter the characteristics. Please take this into consideration when designing patterns and layout.
5. This product has been designed and manufactured for use in ordinary electronic equipment, such as AV equipment, electric home appliances, office machines and communication equipment. In case of using the products for highly sensitive applications such as medical, aviation, aerospace and security, the set makers shall require to include measures necessary to meet product safety requirements of such specific applications. Such measure may include additional protection circuits and redundant circuits, for example.
6. The card specifications are provided by the above manufactures. Products by other manufactures may not be compliant with these specifications and are subject to change without prior notice.

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